I hereby certify that this correspondence is being transmitted to Mail Stop AF, U.S. Patent and Trademark Office via facsimile number 571-273-8300, on September 12, 2005. Kim M. Ramsey

#### RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE **EXAMINING GROUP 2811**

PATENT APPLICATION Docket No. 5038-358 (Intel) RECEIVED **CENTRAL FAX CENTER** 

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SEP 1 2 2005

In re application of: Chuan Hu and Daoqiang Lu

Assignee:

Intel Corporation

Confirmation No. 3995

Serial No.:

10/797,755

Examiner: Owens, Douglas W.

Filed:

For:

March 9, 2004

Group Art Unit: 2811

FLUXLESS DIE-TO-HEAT SPREADER BONDING USING

THERMAL INTERFACE MATERIAL

Date:

September 12, 2005

MAIL STOP AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Responsive to the Final Office Action dated June 30, 2005, enclosed is an Amendment After Final Rejection in the above-identified application. The fee has been calculated as shown below.

	CLAIM	S AS AMENI	DED				
For:	Number After Amendment	Previous Number	Extra		Rate		Additional Fee
Total Claims	17	-21*	0	x	\$50		\$0
Independent Claims	3	-3**	0	×	\$200	=	\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT							\$0

<sup>\*</sup>greater of twenty (20) or number for which fee has been paid \*\*greater of three (3) or number for which fee has been paid

Any deficiency or overpayment should be charged or credited to Deposit Account No. 13-図 1703.

Customer No. 20575

Respectfully submitted,

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PAGE 1/9 \* RCVD AT 9/12/2005 7:07:04 PM (Eastern Daylight Time) \* SVR:USPTO-EFXRF-6/31 \* DNIS:2738300 \* CSID:5032744622 \* DURATION (mm-ss):02-34

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## AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, dated June 30, 2005, Paper No. 20050623, please amend the application as follows.

- Amendments to the Specification begin on page 2 of this paper.
- Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.
- Remarks/Arguments begin on page 7 of this paper.

I hereby certify that this correspondence is being transmitted to Mail Stop AF, U.S. Patent and Trademark Office via facsimile number 571-273-8300, 96 September 42, 2905

Kim M. Ramsey

Application No. 10/797,755